

ABSTRACT

According to one exemplary embodiment, a structure comprises a laminate substrate having a top surface for receiving a semiconductor die. The structure further comprises an antenna element situated on the top surface of the laminate substrate, where the antenna element is coupled to a laminate substrate bond pad. For example, the antenna element may also be coupled to the laminate substrate bond pad by a trace on the top surface of the laminate substrate. According to this exemplary embodiment, the structure further comprises a bonding wire that provides an electrical connection between the laminate substrate bond pad and a semiconductor die bond pad. For example, the input impedance of the antenna element coupled to the laminate substrate bond pad may match the output impedance at the semiconductor die bond pad. The structure may further comprise a capacitor coupled to the antenna element.